

# AFE8190 16-Channel RF Transceiver with Feedback Paths

## 1 Features

- Sixteen RF sampling 12GSPS transmit DACs
- Sixteen RF sampling 5GSPS receive ADCs
- Quad RF sampling 5GSPS feedback ADCs
- Maximum RF signal bandwidth:
  - TX/FB: 800MHz.
  - RX: 600MHz
- RF frequency range: up to 7.2GHz
- Digital Step Attenuators (DSA):
  - TX: 39dB range, 1dB analog and 0.125dB digital steps
  - RX: 30dB range, 1dB step
  - FB: 25dB range, 1dB step
- Single DUC/DDCs per chain
- Supports TDD operation with fast switching between TX and RX
- Internal PLL/VCO to generate DAC/ADC clocks
  - Optional external CLK at DAC or ADC rate
- Digital Data Interface:
  - JESD204B and JESD204C
  - 16 SerDes transceivers up to 32.5Gbps
  - 8b/10b and 64b/66b Encoding
  - 12-bit, 16-bit, 24-bit and 32-bit resolution
  - Subclass 1 multi-device synchronization
- Package:
  - 23mm × 23mm FCBGA, 0.8mm pitch

## 2 Applications

- Macro remote radio unit (RRU)
- Active antenna system mMIMO (AAS)
- Small cell base station
- Distributed Antenna Systems (DAS)
- Repeater

## 3 Description

The AFE8190 is a high performance, wide bandwidth multi-channels transceiver, integrating sixteen RF sampling transmitter chains, sixteen RF sampling receiver chains and four separate RF sampling auxiliary chains (feedback paths). The high dynamic range of the transmitter and receiver chains allows generating and receiving 3G, 4G and 5G signals for wireless base stations, while the wide bandwidth capability makes the AFE8190 an excellent choice for multi-band 4G and 5G base stations.

Each receiver chain includes a 30dB range DSA (Digital Step Attenuator), followed by a 5GSPS ADC (analog-to-digital converter). Each receiver channel has analog peak power detectors and digital peak and power detectors to assist an external or internal autonomous automatic gain controller, and RF overload detectors for device reliability protection. The single digital down converters (DDC) provides up to 600MHz of signal BW.

Each transmitter chain includes a digital up converters (DUCs) supporting up to 800MHz of signal bandwidth. The output of the DUCs drives a 12GSPS DAC (digital to analog converter) with a mixed mode output option to enhance 2nd Nyquist operation. The DAC output includes a variable gain amplifier (TX DSA) with 39dB range and 1dB analog and 0.125dB digital steps.

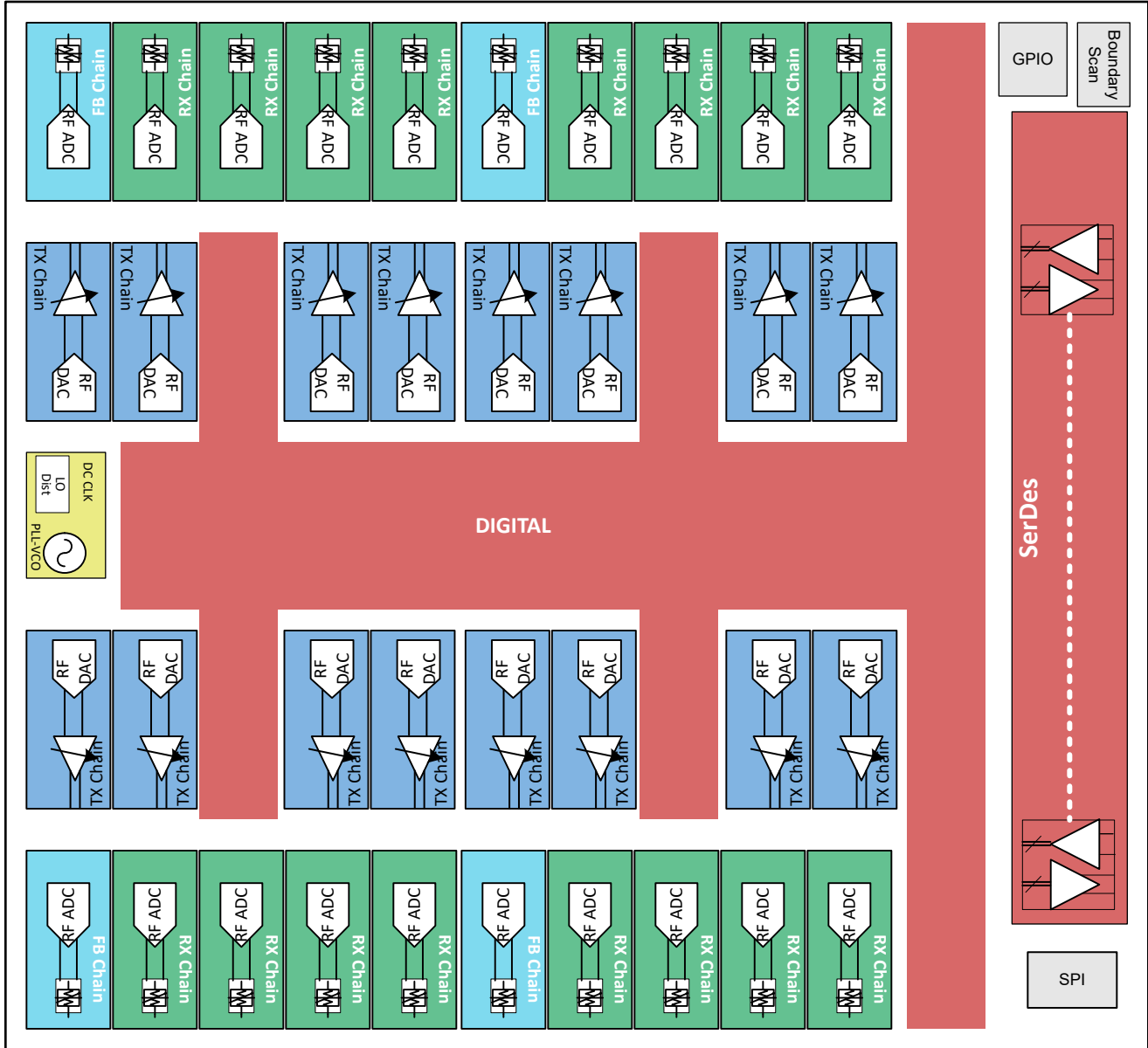
### Package Information

PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE SIZE <sup>(2)</sup>
AFE8190	AMJ (FCBGA, 784)	23mm × 23mm

(1) For all available packages, see [Section 6](#).

(2) The package size (length × width) is a nominal value and includes pins, where applicable.





**Functional Block Diagram**

## Table of Contents

<b>1 Features</b> .....	1	4.3 Trademarks.....	4
<b>2 Applications</b> .....	1	4.4 Electrostatic Discharge Caution.....	4
<b>3 Description</b> .....	1	4.5 Glossary.....	4
<b>4 Device and Documentation Support</b> .....	4	<b>5 Revision History</b> .....	4
4.1 Receiving Notification of Documentation Updates.....	4	<b>6 Mechanical, Packaging, and Orderable Information</b> ....	4
4.2 Support Resources.....	4	6.1 Tray Information.....	5

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## 4 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 4.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 4.2 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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### 4.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.  
All trademarks are the property of their respective owners.

### 4.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 4.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 5 Revision History

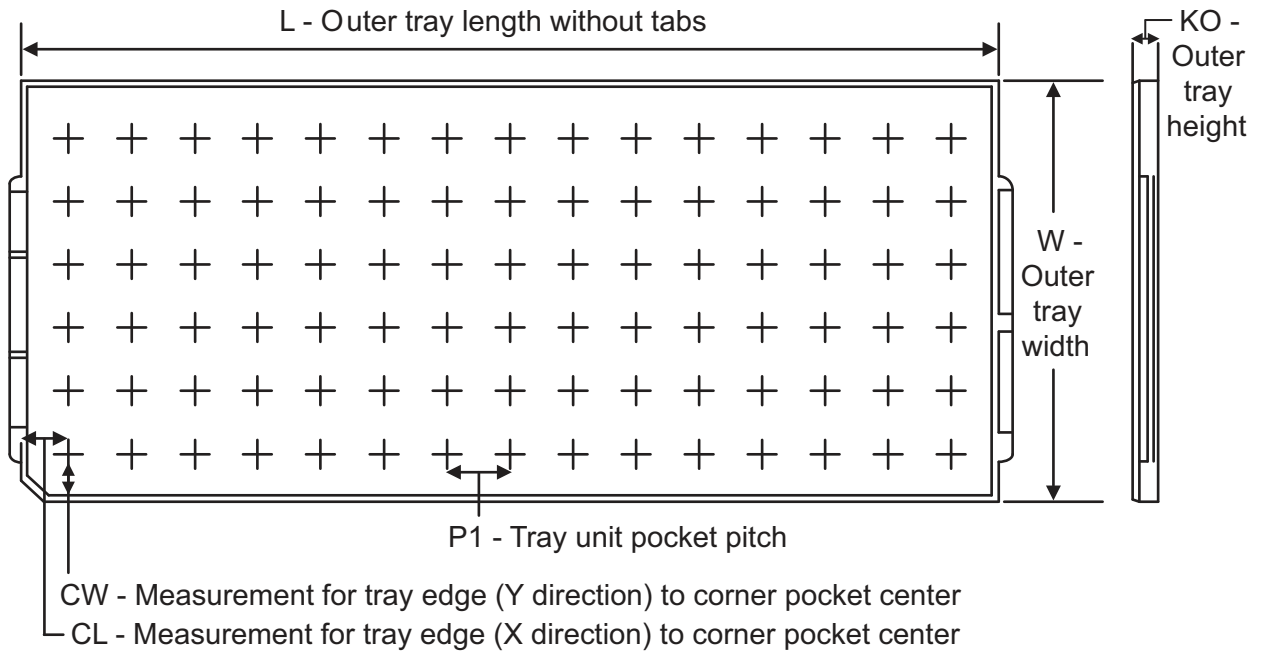
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
September 2024	*	Initial Release

## 6 Mechanical, Packaging, and Orderable Information

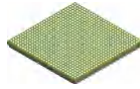
The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## 6.1 Tray Information



Chamfer on Tray corner indicates Pin 1 orientation of packed units.

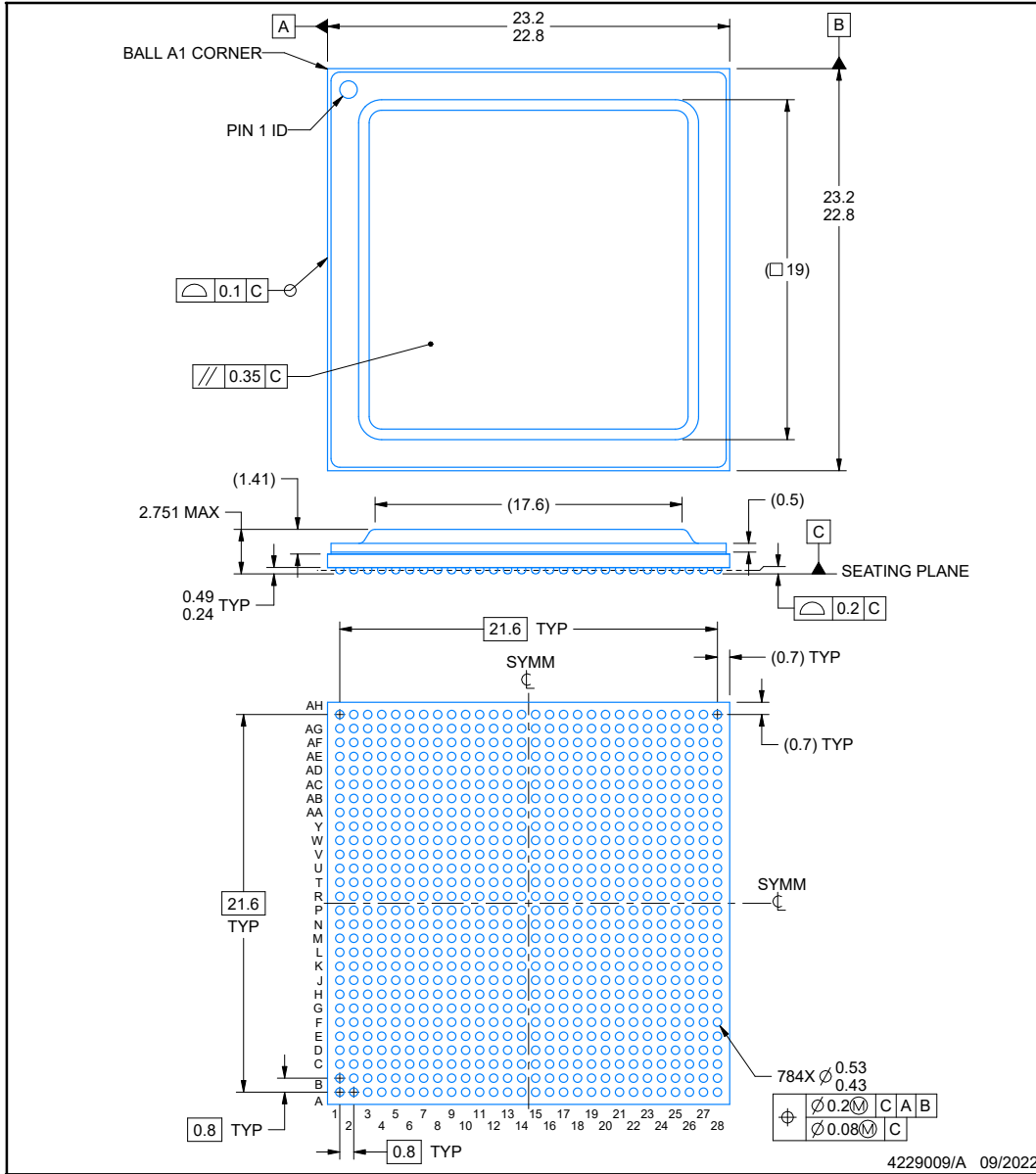
Device	Package Type	Package Name	Pins	SPQ	Unit Array Matrix	Max Temp. (Deg C)	L (mm)	W (mm)	K0 (mm)	P1 (mm)	CL (mm)	CW (mm)
AFE8190IAMJ	FCBGA	AMJ	784	60	150	5 X 12	315	135.9	12190	25.5	17.25	16.95



**AMJ0784A**

**PACKAGE OUTLINE**  
**FCBGA - 2.751 mm max height**

FLIP CHIP BALL GRID ARRAY



NOTES:

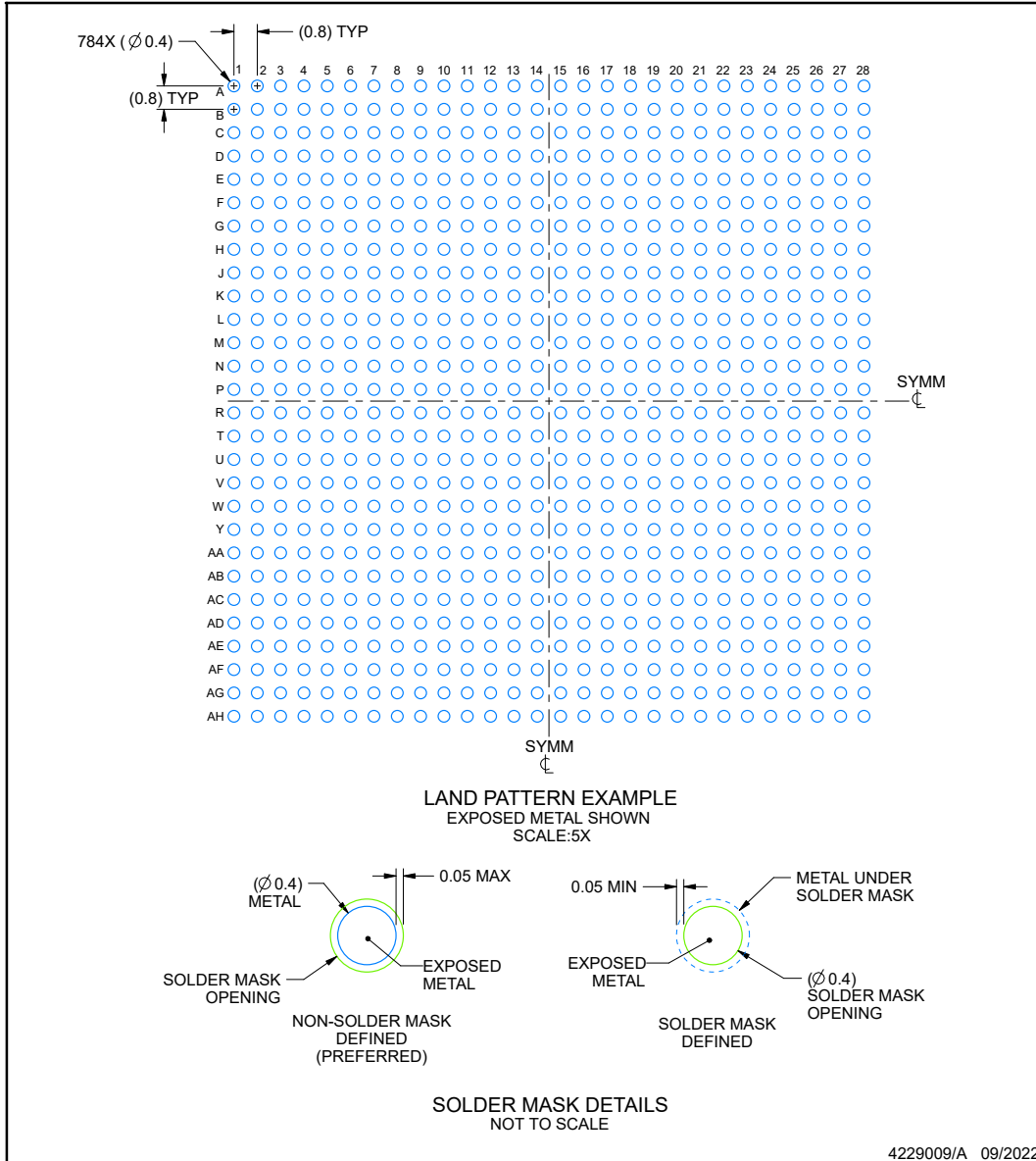
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

**EXAMPLE BOARD LAYOUT**

**AMJ0784A**

**FCBGA - 2.751 mm max height**

FLIP CHIP BALL GRID ARRAY



NOTES: (continued)

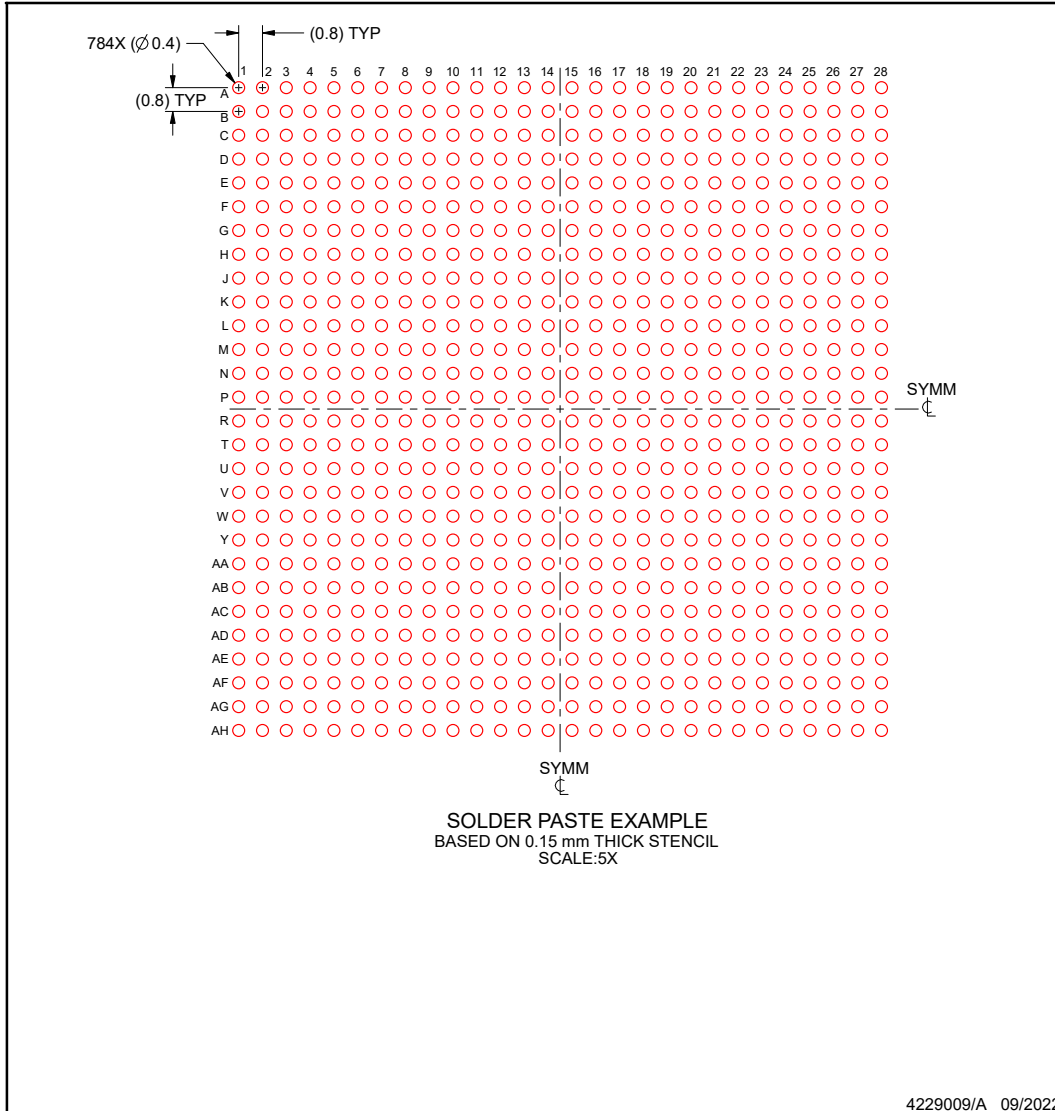
- 3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For information, see Texas Instruments literature number SPRU811 ([www.ti.com/lit/spru811](http://www.ti.com/lit/spru811)).

## EXAMPLE STENCIL DESIGN

**AMJ0784A**

**FCBGA - 2.751 mm max height**

FLIP CHIP BALL GRID ARRAY



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
AFE8190IAMJ	ACTIVE	FCBGA	AMJ	784	60	RoHS & Green	SNAGCU	Level-3-260C-168 HR	-40 to 85	AFE8190	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TRAY**


Chamfer on Tray corner indicates Pin 1 orientation of packed units.

\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (µm)	P1 (mm)	CL (mm)	CW (mm)
AFE8190IAMJ	AMJ	FCBGA	784	60	5 X 12	150	315	135.9	12190	25.5	17.25	16.95

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